

LNJ810C63RA

High Bright Surface Mounting Chip LED

SV (Side View) -Case Type

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Power dissipation	P_D	55	mW
Forward current	I_F	20	mA
Pulse forward current *	I_{FP}	60	mA
Reverse voltage	V_R	4	V
Operating ambient temperature	T_{opr}	-25 to +80	$^\circ\text{C}$
Storage temperature	T_{stg}	-30 to +85	$^\circ\text{C}$

■ Lighting Color

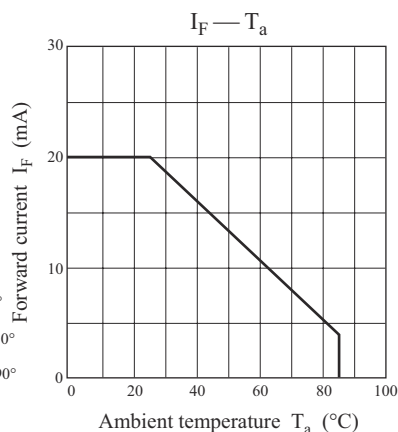
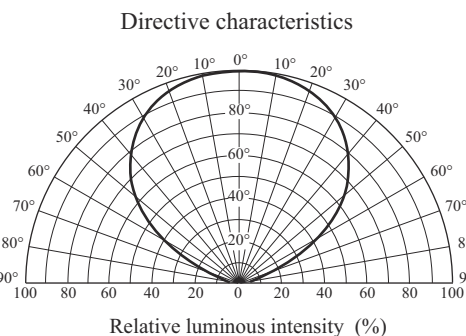
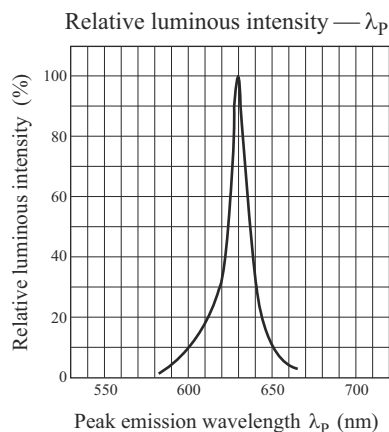
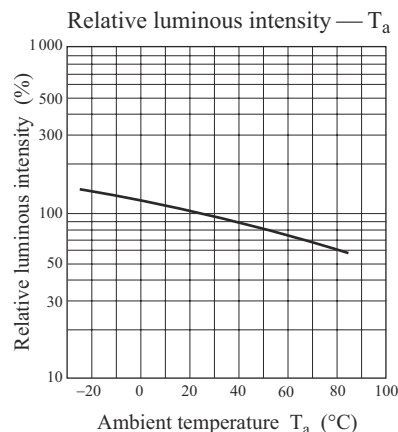
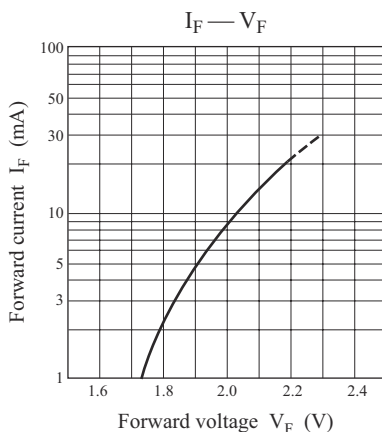
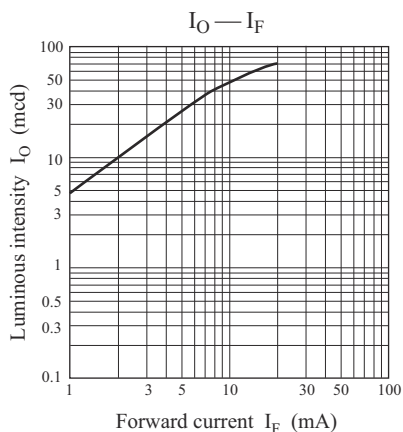
- Orange

Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

■ Electro-Optical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

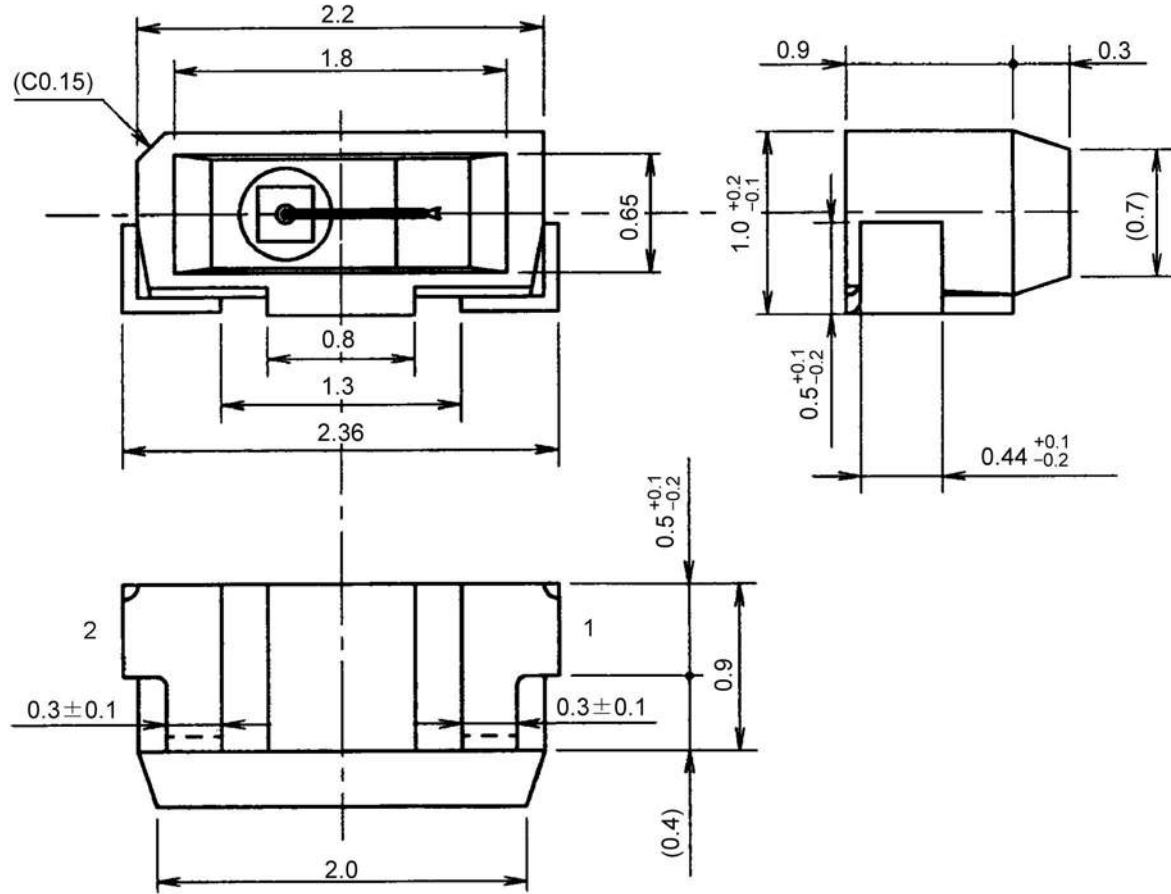
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity *	I_O	$I_F = 10\text{ mA}$	25	48		mcd
Reverse current	I_R	$V_R = 4\text{ V}$			100	μA
Forward voltage	V_F	$I_F = 10\text{ mA}$		2.03	2.50	V
Peak emission wavelength	λ_p	$I_F = 10\text{ mA}$		630		nm
Spectral half band width	$\Delta\lambda$	$I_F = 10\text{ mA}$		15		nm

Note) *: Measurement tolerance: $\pm 20\%$



■ Package (Unit: mm)

LLDFSR2J1000



- Pin name
- 1: Anode
- 2: Cathode

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